

Glossary

(Reference Only - Not A Part of the Specification)

5	10	semiconductor component
	12	supporting substrate
	14	terminal contacts (10)
	16	substrate contacts (12)
	18	capillary dispensing apparatus
10	18NF	no flow dispensing apparatus
	20	capillary underfill material
	20NF	no flow underfill material
	22	capillary underfill layer
	22NF	no flow underfill layer
15	27	non-conductive particles
	28	semiconductor component
	29	Ni particles
	28	MCM semiconductor component (60)
	30	underfill material
20	32	supporting substrate
	32	MCM supporting substrate (60)
	34	substrate contacts (32)
	34	MCM substrate contacts (32MCM)
	36	terminal contacts (28)
25	38	solder mask (32)
	40	openings (38)
	42	micro particles (30)
	44	polymer base material (30)
	46	electrical connections (28-34)
30	46	MCM electrical connections (28MCM-32MCM)
	48	pads (28)
	50	underfill layer
	50	MCM underfill layer (MCM)
	52	solder layer
35	60	system

62 edge connector (60)

64 conductor (60)